4th Topical Meeting On

ELECTRICAL PERFORMANCE OF ELECTRONIC PACKAGING

October 2-4, 1995
Portland, Oregon

FIRST CALL FOR PAPERS

Co-Chairs: A. Deutsch, IBM Corporation, V. K. Tripathi, Oregon State University

The general subject of the meeting is the electrical design, analysis, and characterization of electronic interconnections and packaging for performance-driven, high speed/high complexity electronic systems. A forum will be provided for the discussion of the following topics as they relate to chip-to-chip and on-chip interconnections in electronic systems:

- Package analysis, including numerical methods and algorithms; electromagnetic analysis tools; advances in transmission line techniques.
- New and innovative interconnect and packaging structures and their electrical performance.
- RF/Microwave packaging structures and their electrical performance.
- MMIC modules and high density packaging.
- Experimental characterization techniques and testing procedures.
- EMC/EMI effects; prediction and measurement of radiation from inter-connect structures and packaged systems.
- Electrical requirements, limits of performance.
- Novel designs, design methods, wire placement and routing systems.
- Low cost, high volume packaging
- Optoelectronic packaging; structure and system applications.
- Packaging concerns for wireless communication; design and modelling.
- Current and future issues related to on-chip interconnections; performance limits.

Additional information may be obtained from A. Deutsch (phone: 914-945-2858, Fax 914-945-2141, e-mail deutsch@watson.ibm.com) or V. K. Tripathi (phone: 503-737-2988, Fax 503-737-1300, e-mail vkt@ece.orst.edu).

Authors are invited to submit papers describing new technical contributions in the areas broadly covered above. The original and three copies of a summary, not to exceed three pages, including illustrations, are required for paper selection. All papers must be written in English. The title of the paper and the names and affiliations of all the authors including complete mailing address, telephone, FAX number and e-mail, must appear on the first page of the summary, as well as a 35-word abstract. FAX and e-mail are absolutely necessary since all paper acceptance notifications and further communications will be done via one of these media. If the paper is accepted, the summary will be reproduced, as is, in the meeting's digest. **AN IEEE TRANSFER OF COPYRIGHT, FOUND IN MOST IEEE JOURNALS, MUST ACCOMPANY EACH SUBMISSION.**

Submission should be sent, no later than **June 7, 1995**, to the address below. Several half and full-day SHORT COURSES will be offered on Sunday, October 1 in conjunction with the topical meeting. Proposals for these courses must be submitted to the co-chairs by April 28, 1995.

PRODUCT DISPLAYS: Parties interested in displaying products and software packages at this meeting should contact the address below.

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